

Product Overview

The Qorvo® QPA5219 is a three-stage power amplifier (PA) designed for Wi-Fi. The compact form factor and integrated matching minimizes layout area in the application.

Performance is focused on optimizing for power consumption while maintaining the highest linear output power and leading edge throughput that leads to greater ranges.

The design significantly minimizes external component needs leading to a simplified board implementation and more consistent performance at a system level over a variety of conditions

The QPA5219 integrates a 2 GHz power amplifier (PA), regulator and a power detector for improved accuracy.

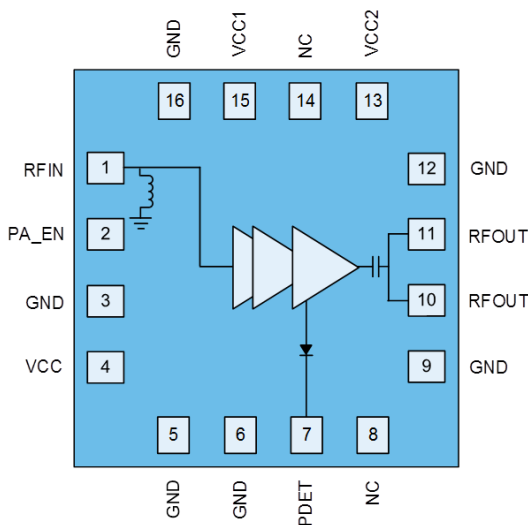


16 Pin 3x3 mm Laminate Package

Key Features

- 2400-2500 MHz
- P_{OUT} = +24dBm MCS8/9 VHT20/40 -35dB Dynamic EVM
- P_{OUT} = +25dBm MCS7 HT20 -30dB Dynamic EVM
- P_{OUT} = +26dBm 802.11g -28dB Dynamic EVM
- P_{OUT} = +28.5dBm 802.11b @ Spectral Mask Compliance
- Optimized for +5 V Operation
- 32 dB Tx Gain
- Integrated DC Power Detector
- MCS11 and 3.3V Capable

Functional Block Diagram



Top View

Applications

- Access Points
- Wireless Routers
- Client Equipment
- Customer Premise Equipment
- Internet of Things

Ordering Information

Part Number	Description
QPA5219SB	Sample bag with 5 pieces
QPA5219SQ	Sample bag with 25 pieces
QPA5219SR	7" reel with 100 pieces
QPA5219TR7	7" reel with 2500 pieces
QPA5219TR13	13" reel with 5000 pieces
QPA5219PCK401	Assembled Evaluation Board + 5 pcs

Absolute Maximum Ratings

Parameter	Conditions	Rating
DC Supply Voltage		-0.5 to +6 V
PA Enable Voltage		-0.5 to V_{CC}
Storage Temperature		-40 to 150 °C
Junction Temperature	MTTF ~ 30,300,000 hrs (3,452 Years)	190 °C
	MTTF ~ 4,790,000 hrs (546 Years)	200 °C
	MTTF ~ 2,020,000 hrs (230 Years)	210 °C
	MTTF ~ 1,030,000 hrs (118 Years)	218 °C
RF Input Power at RFIN	Into 50 Ω Load for 802.11a/n/ac (No Damage), Transmit Mode	+12 dBm

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability.

Recommended Operating Conditions

Parameter	Min.	Typ.	Max.	Units
Operating Frequency	2412		2484	MHz
Extended Operating Frequency	2400		2500	MHz
Device Voltage (V_{CC})	+4.5	+5	+5.5	V
PA Enable Voltage – High	+1.7	+3	V_{CC}	V
PA Enable Voltage - Low	0		+0.5	V
$T_{OPERATING}^*$	-40		+85	°C

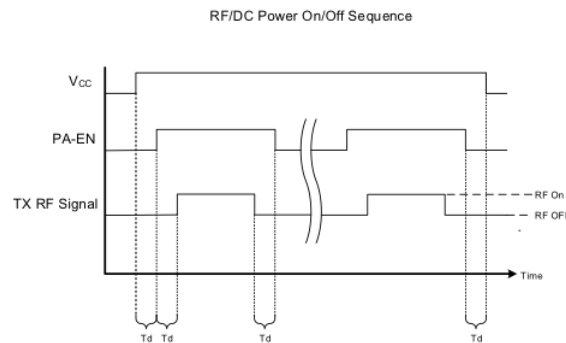
Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all recommended operating conditions. * $T_{OPERATING}$ is temperature at the package ground.

Electrical Specifications

Parameter	Conditions	Min.	Typ.	Max.	Units
TRANSMIT (RFIN-RFOUT) MODE					
Unless otherwise noted: $V_{CC}=5V$, $T=+25^{\circ}C$, $PA_EN=High$					
11ac VHT40 Output Power	MCS11 1024QAM		21		dBm
				-40	dB
11ac VHT20/40 Output Power	MCS8/9 256QAM	23	24		dBm
					-35
11n HT20 Output Power	MCS7 64QAM	23.5	25		dBm
Dynamic EVM					-30
11g Output Power	OFDM 54MBps	24.5	26		dBm
Dynamic EVM					-28
Margin to VHT40 Spectral Mask	$P_{OUT} = +25.5$ dBm, 11ac MCS0		3	0	dBc
Margin to HT20 Spectral Mask	$P_{OUT} = +26$ dBm, 11n MCS0		3	0	dBc
Margin to 802.11g Spectral Mask	$P_{OUT} = +27$ dBm, OFDM 54MBps		3	0	dBc
Margin to 802.11b Spectral Mask	$P_{OUT} = +28.5$ dBm, 1 MBps		3	0	dBc
Gain		30	32		dB
Gain Flatness	Across any 40 MHz Channel	-0.35		+0.35	dB
RFIN Port Return Loss		10	17		dB
RFOUT Port Return Loss		7	9		dB

Parameter	Conditions	Min.	Typ.	Max.	Units
Quiescent Current	RF Off		210	250	mA
Operating Current	P _{OUT} = +24 dBm		335	390	mA
	P _{OUT} = +28.5 dBm		500	600	mA
2 nd Harmonics	P _{OUT} = +28.5 dBm 802.11b 1 Mbps		-35	-30	dBm/MHz
3 rd Harmonics	P _{OUT} = +28.5 dBm 802.11b 1 Mbps		-60	-50	dBm/MHz
DC Power Detect Voltage	RF Off		0.14		V
	P _{OUT} = +24 dBm		0.46		V
	P _{OUT} = +26 dBm		0.55		V
	P _{OUT} = +28.5 dBm		0.74		V
GENERAL SPECIFICATIONS	Unless otherwise noted: V_{CC}=5V, T=+25°C				
Leakage Current			0.1	0.5	μA
Control Current - Low			0.1		μA
TX Output P _{1dB}	CW		+32		dBm
Ramp ON/OFF Time	10<->90% Ref from Control Voltage to RF Power		300		nS
PA Stability - Output VSWR	CW No Spurious above -50dBm/MHz		4:1		
Output Power Range		0		28.5	dBm
Thermal Resistance, θ _{jc}	Junction to case		40		°C/W

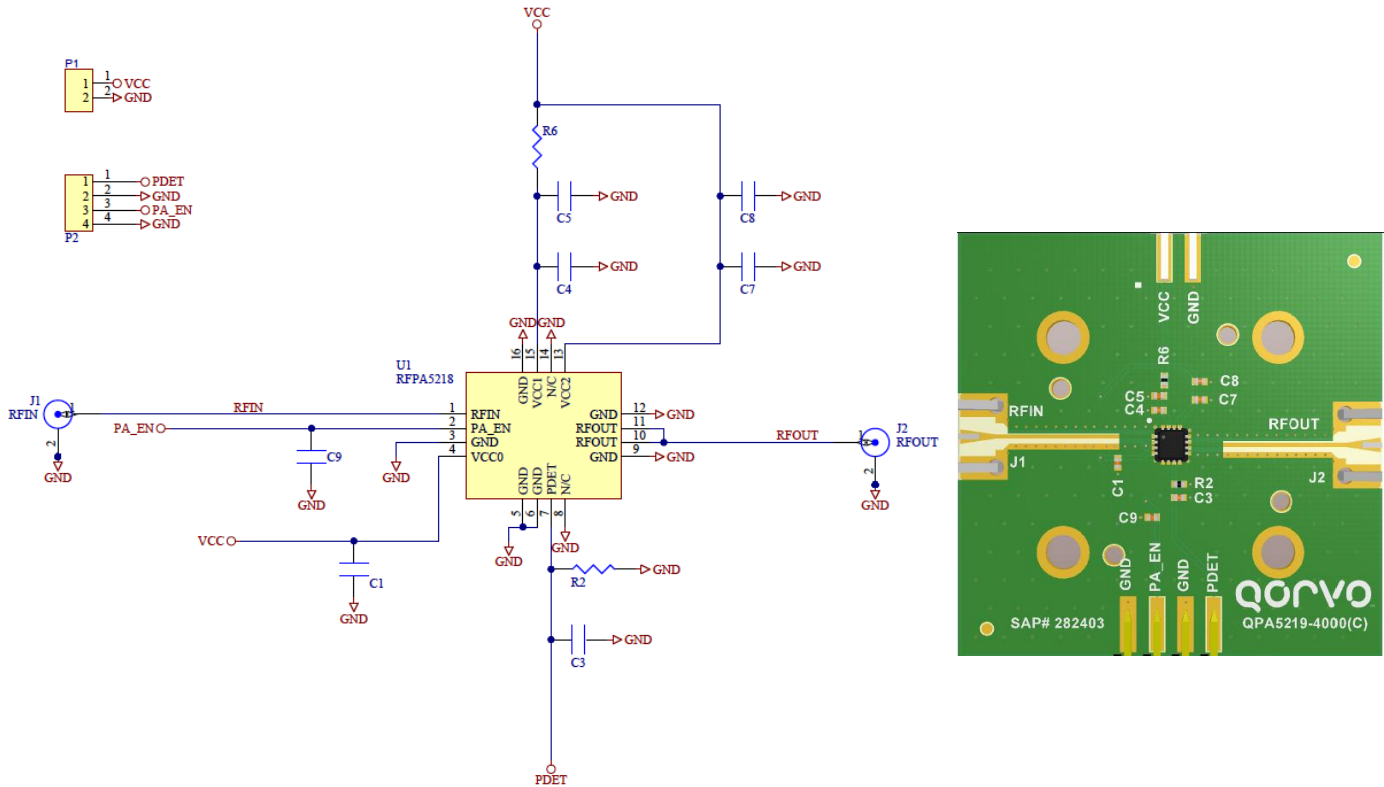
Timing Diagram



Note: Observe the timing sequence shown in the diagram above and described below.
DC and RF signal levels per data sheet specification

- Apply V_{CC} prior to turning on or pulsing PA enable.
- Turn off PA enable prior to turning off V_{CC}.
- Turn on PA enable prior to applying RF signal.
- Turn off RF signal prior to turning off PA enable.

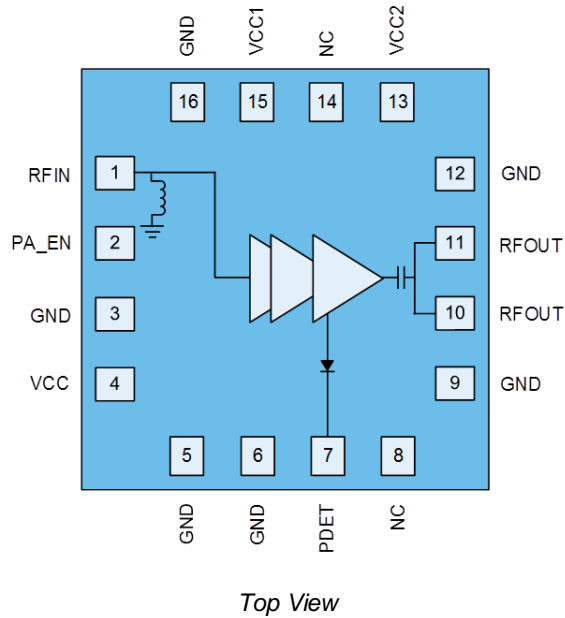
Evaluation Board Schematic and Layout



Bill of Material

Ref. Des.	Value	Description	Manuf.	Part number
-	-	Printed Circuit Board		
U1	-	2.4GHz Wi-Fi Power Amplifier	Qorvo	QPA5219
C4, C7	0.1 μ F	Capacitor, Chip, 10%, 10V, X5R, 0402	Taiyo Yuden	
C1, C5, C8	2.2 μ F	Capacitor, Chip, 20%, 6.3V, X5R, 0402	Murata	
R6	0 Ω	Resistor, Chip, 5%, 1/10W, 0402	Kamaya	
R2	27K Ω	Resistor, Chip, 5%, 1/16W, 0402	Panasonic	
C3, C9	-	Do Not Install		

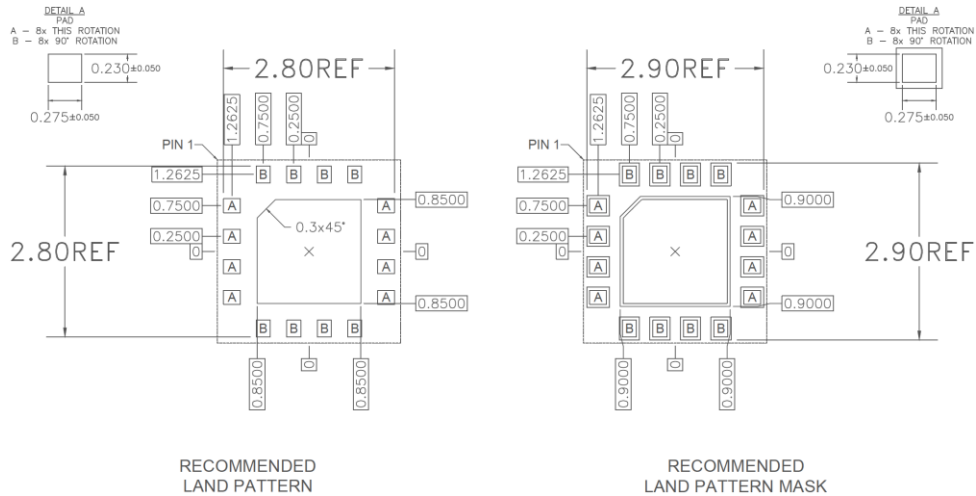
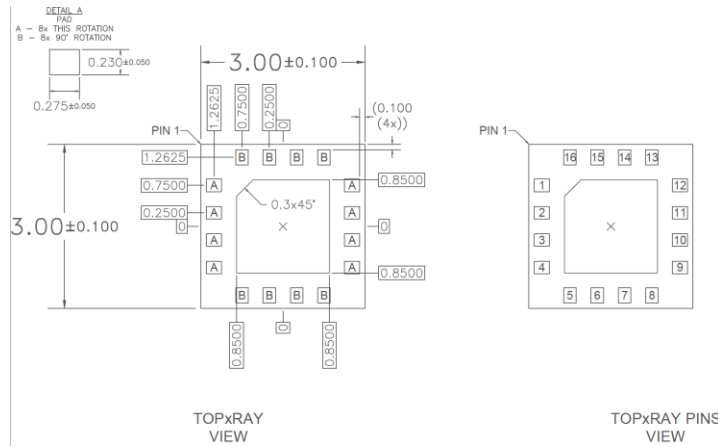
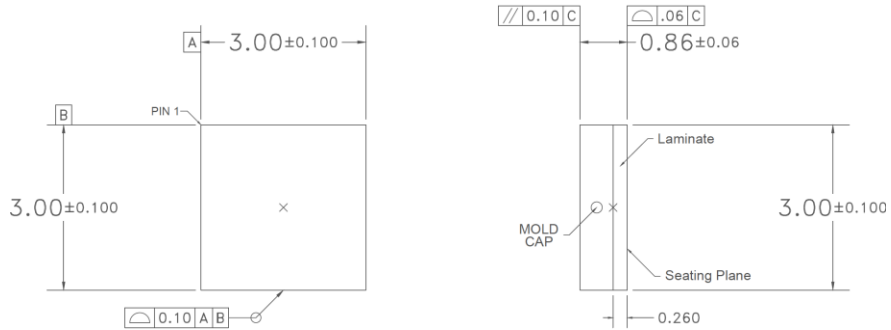
Pin Configuration and Description



Pin Number	Label	Description
1	RFIN	RF input port for the PA. This port is matched to 50Ω and DC shorted internally.
2	PA_EN	Control voltage.
3	GND	Ground connection.
4	VCC	Supply voltage. See applications schematic for biasing and bypassing components.
5	GND	Ground connection.
6	GND	Ground connection.
7	PDET	Power Detector voltage for the PA. May need external series R/shunt C to adjust voltage level and to filter RF noise.
8	NC	No connect. This pin is not connected internally and can be left floating or connected to ground.
9	GND	Ground connection
10	RFOUT	RF output port. This port is matched to 50Ω and DC blocked internally.
11	RFOUT	RF output port. This port is matched to 50Ω and DC blocked internally.
12	GND	Ground connection
13	VCC2	Supply voltage. See applications schematic for biasing and bypassing components.
14	NC	No connect. This pin is not connected internally and can be left floating or connected to ground.
15	VCC1	Supply voltage. See applications schematic for biasing and bypassing components.
16	GND	Ground connection
Backside Paddle	GND	RF/DC ground. Use recommended via pattern to minimize inductance and thermal resistance. See PCB Mounting Pattern for suggested footprint.

Mechanical Information

Dimensions and PCB Mounting Pattern



Notes:

1. All dimensions are in mm. Angles are in degrees.
2. Dimension and tolerance formats conform to ASME Y14.4M-1994.
3. The terminal #1 identifier and terminal numbering conform to JESD 95-1 SPP-012.

Handling Precautions

Parameter	Rating	Standard
ESD – Human Body Model (HBM)	Class 1C	ANSI/ESD/JEDEC JS-001
ESD – Charged Device Model (CDM)	Class C3	ANSI/ESD/JEDEC JS-002
MSL – Moisture Sensitivity Level	Level 3	IPC/JEDEC J-STD-020



Caution!

ESD sensitive device

Solderability

Compatible with both lead-free (260 °C max. reflow temperature) and tin/lead (245 °C max. reflow temperature) soldering processes.

Package lead plating: Electrolytic plated Au over Ni

RoHS Compliance

This part is compliant with the 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment), as amended by Directive 2015/863/EU.

This product also has the following attributes:

- Lead free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C₁₅H₁₂Br₄O₂) Free
- SVHC Free



Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations:

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